



Material Content Data Sheet



Sales Product Name	SAK-TC1736-128F80HL AA			Issued		2. August 2018		
MA#	MA000839860							
Package	PG-LQFP-144-10			Weight*		1419.19 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	24.572	1.73	1.73	17314	17314
leadframe	non noble metal	magnesium	7439-95-4	0.538	0.04		379	
	inorganic material	silicon	7440-21-3	2.331	0.16		1642	
	non noble metal	nickel	7440-02-0	10.757	0.76		7579	
	non noble metal	copper	7440-50-8	344.930	24.30	25.26	243048	252648
wire	noble metal	gold	7440-57-5	6.501	0.46	0.46	4580	4580
encapsulation	organic material	carbon black	1333-86-4	5.065	0.36		3569	
	plastics	epoxy resin	-	136.751	9.64		96359	
	inorganic material	silicondioxide	60676-86-0	871.151	61.39	71.39	613840	713768
leadfinish	non noble metal	tin	7440-31-5	9.120	0.64	0.64	6426	6426
plating	noble metal	silver	7440-22-4	3.047	0.21	0.21	2147	2147
glue	plastics	epoxy resin	-	1.106	0.08		779	
	noble metal	silver	7440-22-4	3.319	0.23	0.31	2338	3117
*deviation	< 10%	Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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